

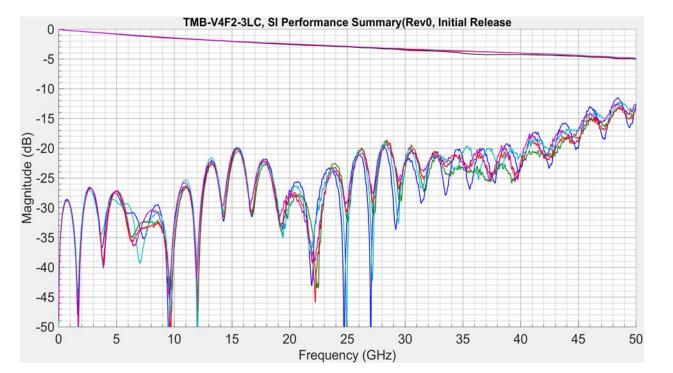
Test and Measurement Performance Report

Part Number TMB-V4F2-3LC

(2.4 mm Vertical Launch CPW Solderless Precision Connector) **Distribution**: *Internal & External Use*



SI Performance Summary (Attenuation & Reflections, Single-Ended)



* 10 connectors are shown, measured in pairs. (5 measurements) For further details regarding testing setup, configurations please see the rest of the report.

REVISION:	ECN INFORMATION:	TITLE: 2.4 mm Vertical Launch CPW			SHEET No.
1	EC No: N/A	Solderless Precision Connector		1 of 8	
	DATE: 04/ 21 / 2020	(TMB-V4F2-3	LC)		1010
DOCUMENT NUMBER:		SI ENGINEER:	DESIGN ENGINEER ENGINEERING MANA		MANAGER
RSI- TMB_V4F2_3LC		R.Stavoli	P. Volkov	E.Soubh	
			TEM	LATE FILENAME: SPM[S	SIZE_A](V.1).DOC

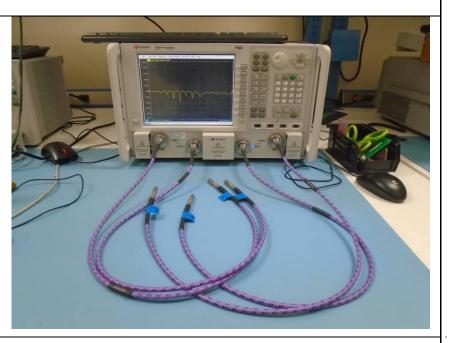


1.0 TEST SETUP AND DUT

Equipment, fixtures, and methods

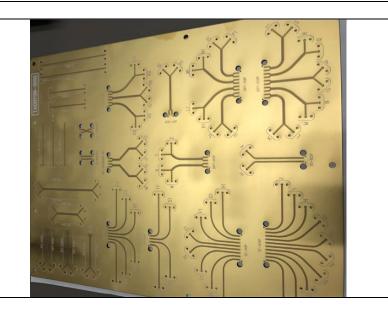
Test method: All data measured from test PCB shown below and a N5227A PNA Network Analyzer

- Calibration was performed up to the
 2. 4mm adapters using calibration kit:
 85056B
- Data was swept from 10 MHz to 50GHz for 5000 points
- Data averaging was turned off.
- Data is not dembedded and includes the board trace/transition and two RF vertical launch CPW precision connectors



Assembly Description

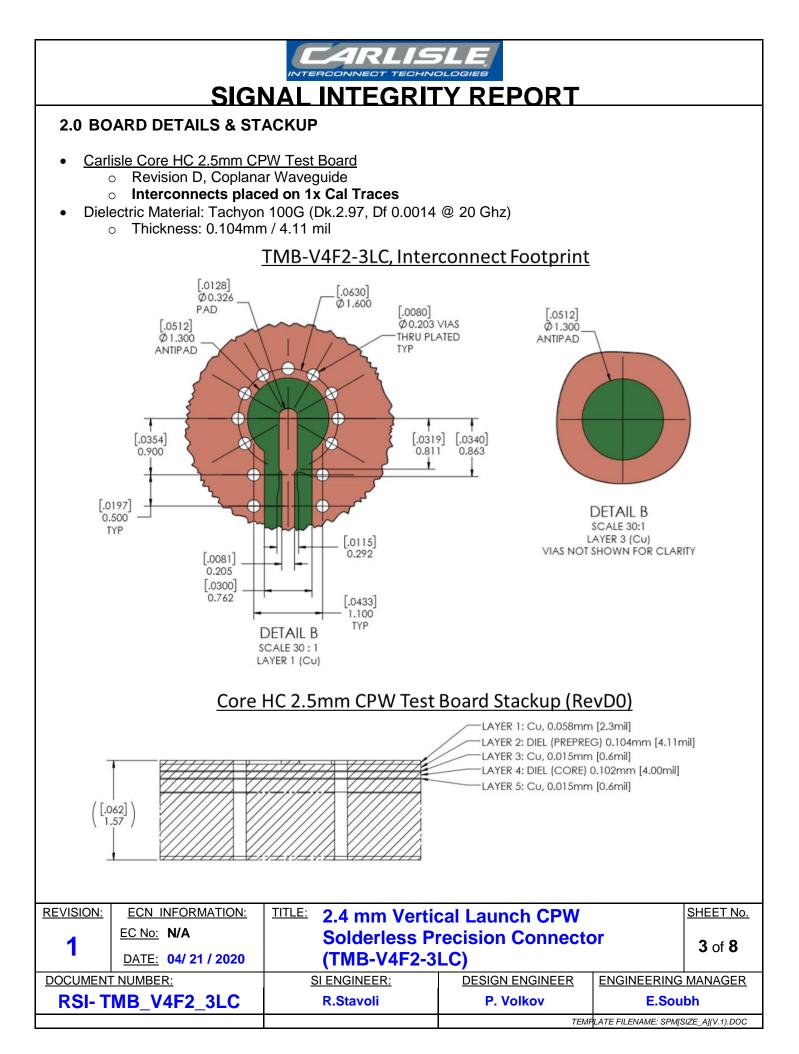
- T&M PN: TMB-V4F2-3LC
- Carlisle DUT PCB: Core HC 2.5mm CPW Test Board (Rev D0)
- Measured on: 1x Cal Trace (SE-1xCal+)
- Port 1: 2.4mm vertical mount CPW
- Port 2: 2.4mm vertical mount CPW



Testing	Samples:

10 Samples	 5 THRU Measurements (5 Channels = 10 samples) -> -Single-Ended
5 Channels	

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1	<u>EC No:</u> N/A	Solderless Precision Connector		2 of 8	
	DATE: 04/ 21 / 2020	(TMB-V4F2-3	LC)		2010
DOCUMENT NUMBER:		<u>SI ENGINEER:</u>	DESIGN ENGINEER ENGINEERING MANA		MANAGER
RSI- TMB_V4F2_3LC		R.Stavoli	P. Volkov E.Soubh		bh
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC			SIZE_A](V.1).DOC		





SIGNAL INTEGRITY REPORT

C) PCB FINISH

1. Surface Protective Plating

- a. All exposed copper on the outer layers shall be plated with a protective surface finish.
- b. All exposed pads, edge fingers and plated through holes shall be ENIG with thickness listed in Table 2.

Table 2: Protective Plating Thickness

Nickel		Immersion Gold	
μm (microinch)		µm (microinch)	
Min.	Max.	Min.	Max.
2.5 (100)	13(512)	0.051 (2)	0.2032 (8)

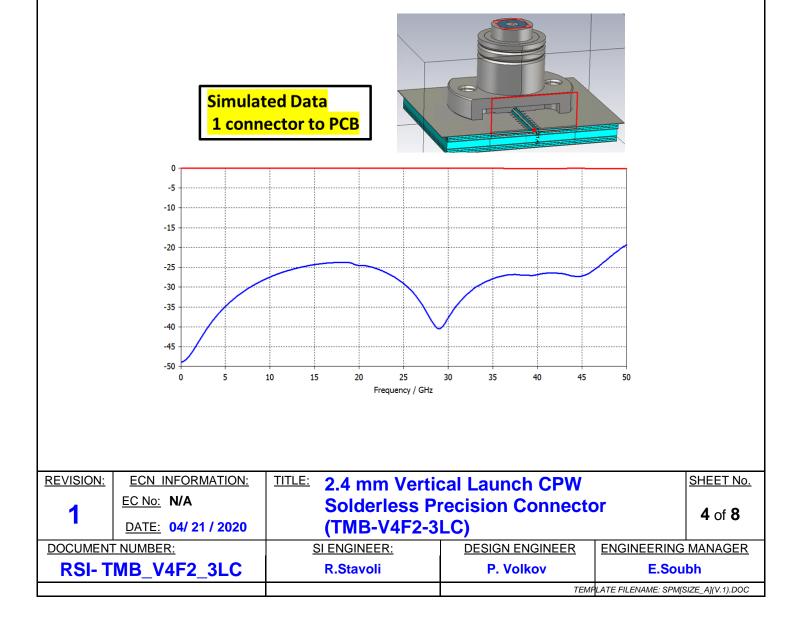
2. Solder Mask

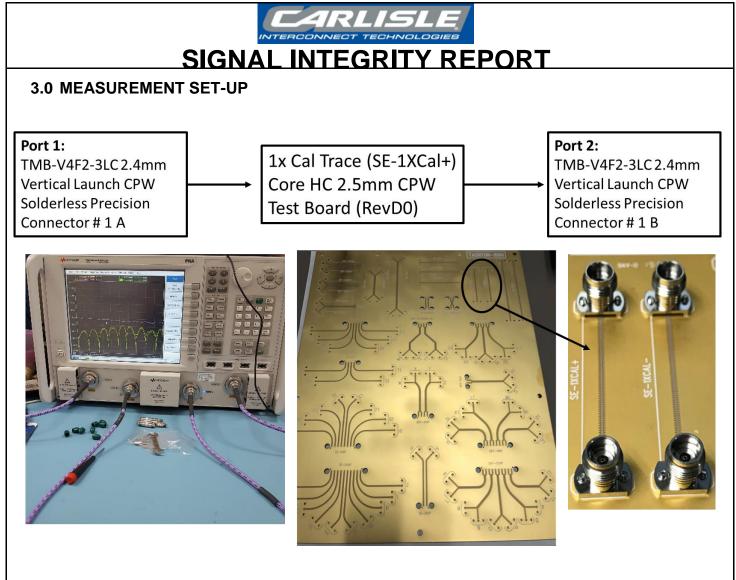
Apply an LPI solder mask to both sides of the board, the solder mask color is defined in the table.

PCB PN	Soldermask color
NA	Green

3. Silkscreen

Silkscreen shall be permanent, non-conductive ink. There shall be no silkscreen on any solderable component pad. Color: White





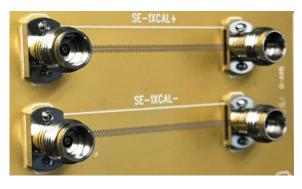
Measurements are not dembedded and include the two 2.4mm vertical launch CPW solderless precision connectors, and the PCB (transition, traces)

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			TEMF	LATE FILENAME: SPM[S	SIZE_A](V.1).DOC



SIGNAL INTEGRITY REPORT

4.0 SIGNAL INTEGRITY RESULTS (CIT: CORE HC 2.5MM CPW PCB, 1X CAL TRACE)



Insertion Loss (S21), 10 connectors measured, 5 measurements

